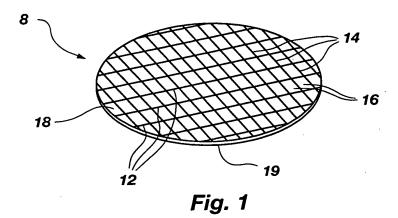
TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES

Inventor: Poo et al. Docket No.: 2269-4885.1US



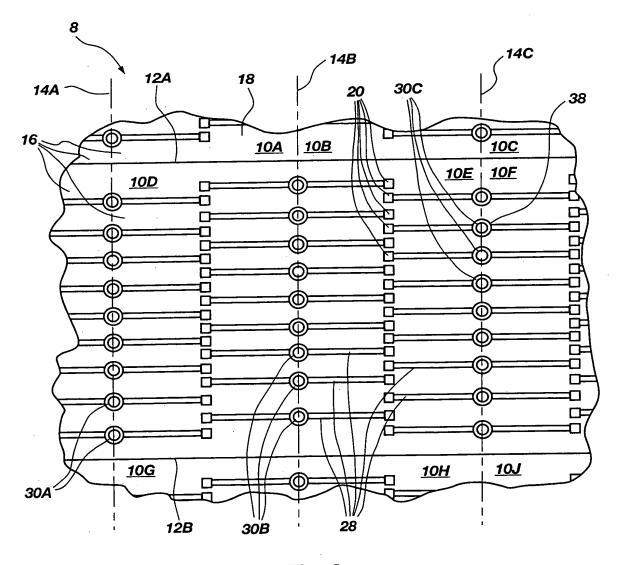
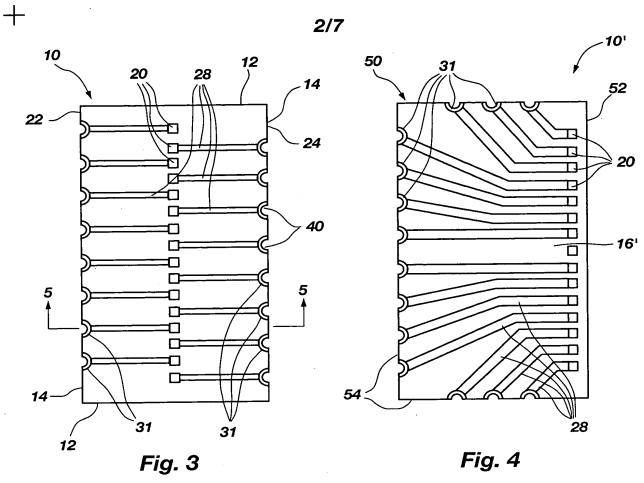


Fig. 2

Inventor: Poo et al. Docket No.: 2269-4885.1US



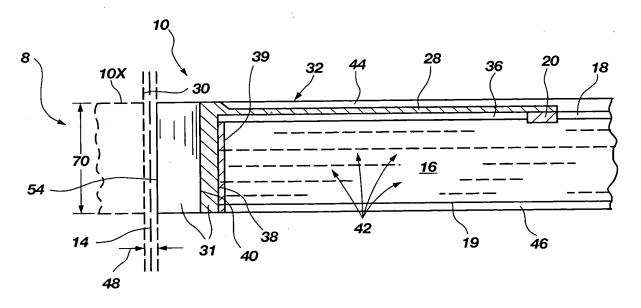
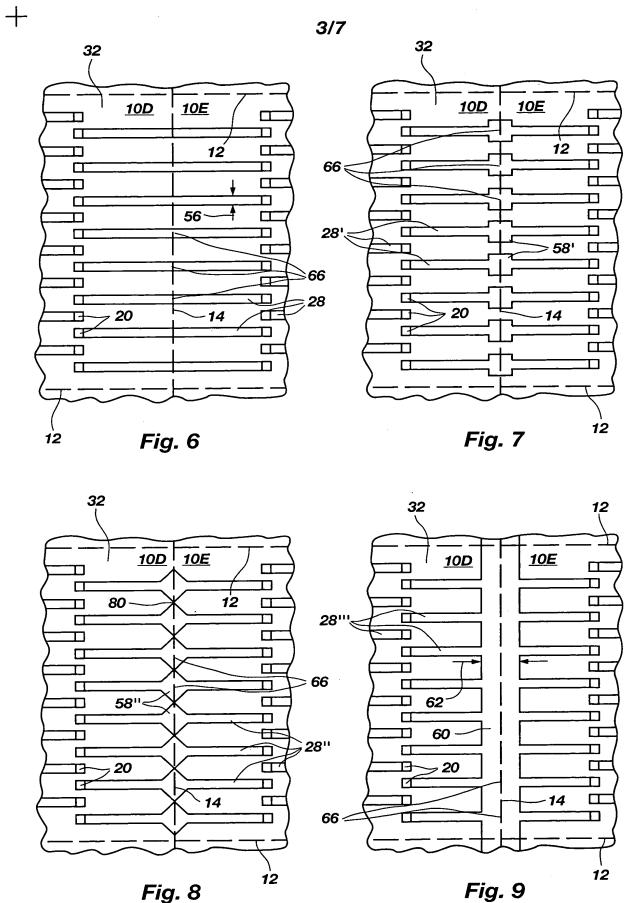
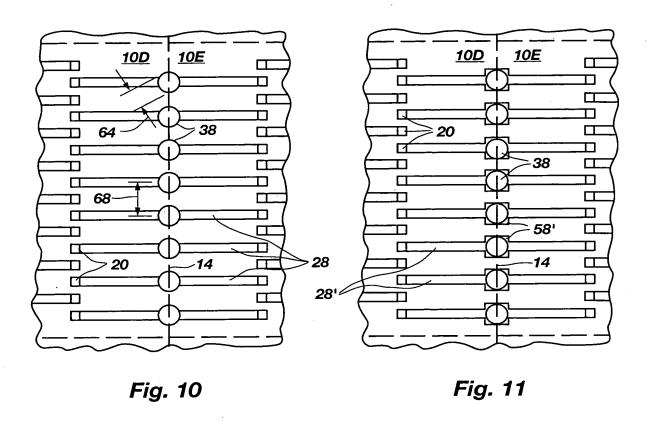


Fig. 5

Inventor: Poo et al. Docket No.: 2269-4885.1US



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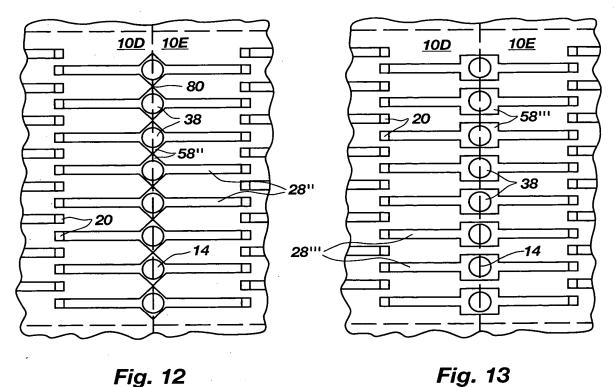


Fig. 13

TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES

Inventor: Poo et al. Docket No.: 2269-4885.1US



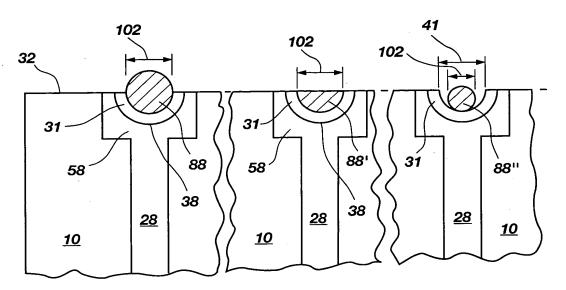


Fig. 20

Fig. 21

Fig. 22

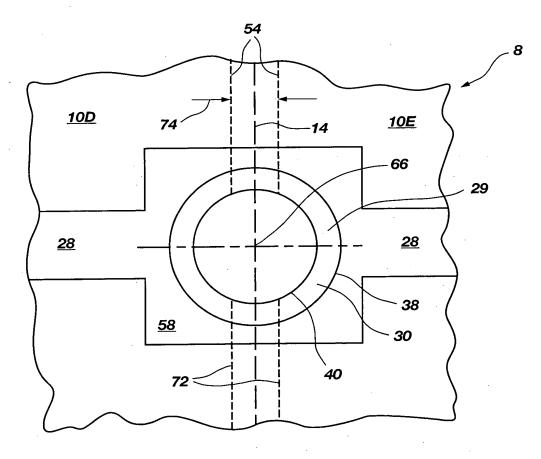
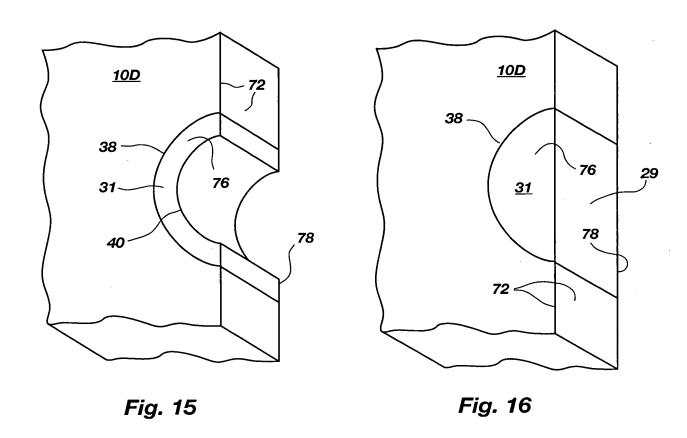


Fig. 14

Inventor: Poo et al.
Docket No.: 2269-4885.1US



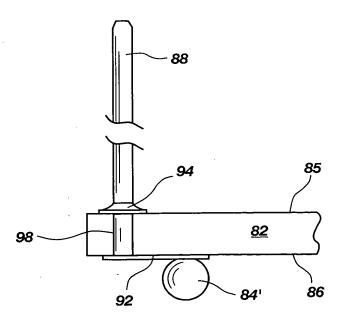
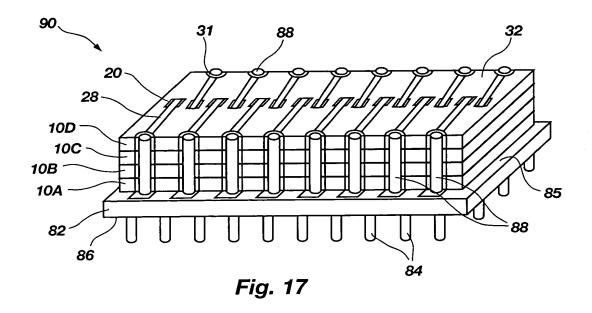


Fig. 19

TITLE: SEMICONDUCTOR DEVICES INCLUDING PERIPHERALLY LOCATED BOND PADS, INTERMEDIATES THEREOF, ASSEMBLIES, AND PACKAGES INCLUDING THE SEMICONDUCTOR DEVICES, AND SUPPORT ELEMENTS FOR THE SEMICONDUCTOR DEVICES Inventor: Poo et al. Docket No.: 2269-4885.1US



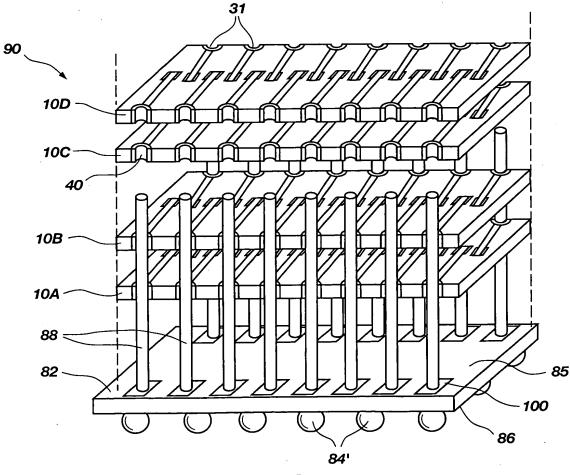


Fig. 18